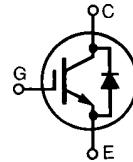


## HiPerFAST™ IGBT with Diode

Short Circuit SOA Capability

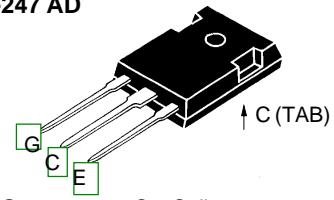
**IXSH 24N60U1**  
**IXSH24N60AU1**

<b>V<sub>CES</sub></b>	<b>I<sub>C25</sub></b>	<b>V<sub>CE(sat)</sub></b>
<b>600 V</b>	<b>48 A</b>	<b>2.2 V</b>
<b>600 V</b>	<b>48 A</b>	<b>2.7 V</b>



Symbol	Test Conditions	Maximum Ratings		
V <sub>CES</sub>	T <sub>J</sub> = 25°C to 150°C	600	V	
V <sub>CGR</sub>	T <sub>J</sub> = 25°C to 150°C; R <sub>GE</sub> = 1 MΩ		V	
V <sub>GES</sub>	Continuous	±20	V	
V <sub>GEM</sub>	Transient	±30	V	
I <sub>C25</sub>	T <sub>C</sub> = 25°C	48	A	
I <sub>C90</sub>	T <sub>C</sub> = 90°C	24	A	
I <sub>CM</sub>	T <sub>C</sub> = 25°C, 1 ms	96	A	
<b>SSOA (RBSOA)</b>	V <sub>GE</sub> = 15 V, T <sub>VJ</sub> = 125°C, R <sub>G</sub> = 10 Ω Clamped inductive load, L = 100 μH	I <sub>CM</sub> = 48 @ 0.8 V <sub>CES</sub>	A	
<b>t<sub>sc</sub> (SCSOA)</b>	V <sub>GE</sub> = 15 V, V <sub>CE</sub> = 360 V, T <sub>J</sub> = 125°C, R <sub>G</sub> = 82 Ω, non-repetitive	10	μs	
P <sub>c</sub>	T <sub>C</sub> = 25°C	150	W	
T <sub>J</sub>		-55 ... +150	°C	
T <sub>JM</sub>		150	°C	
T <sub>stg</sub>		-55 ... +150	°C	
Maximum Lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C	
Maximum Tab temperature for soldering SMD devices for 10 s		260	°C	
M <sub>d</sub>	Mounting torque, TO-247	1.13/10 Nm/lb.in.		
<b>Weight</b>	TO-247 AD	6	g	

TO-247 AD



G = Gate,  
E = Emitter,  
C = Collector,  
TAB = Collector

### Features

- International standard package JEDEC TO-247 AD
- High frequency IGBT and anti-parallel FRED in one package
- 2nd generation HDMOS™ process
- Low V<sub>CE(sat)</sub>
  - for minimum on-state conduction losses
- MOS Gate turn-on
  - drive simplicity
- Fast Recovery Epitaxial Diode (FRED)
  - soft recovery with low I<sub>RM</sub>

### Applications

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

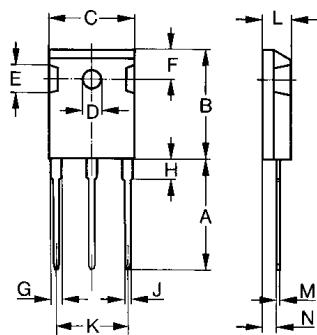
### Advantages

- Space savings (two devices in one package)
- Suitable for surface mounting
- Easy to mount with 1 screw, TO-247 (isolated mounting screw hole)
- Reduces assembly time and cost

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C, unless otherwise specified)	min.	typ.
BV <sub>CES</sub>	I <sub>C</sub> = 750 μA, V <sub>GE</sub> = 0 V	600		V
V <sub>GE(th)</sub>	I <sub>C</sub> = 1.5 mA, V <sub>CE</sub> = V <sub>GE</sub>	3.5		V
I <sub>CES</sub>	V <sub>CE</sub> = 0.8 • V <sub>CES</sub>	T <sub>J</sub> = 25°C	500	μA
	V <sub>GE</sub> = 0 V	T <sub>J</sub> = 125°C	8	mA
I <sub>GES</sub>	V <sub>CE</sub> = 0 V, V <sub>GE</sub> = ±20 V		±100	nA
V <sub>CE(sat)</sub>	I <sub>C</sub> = I <sub>C90</sub> , V <sub>GE</sub> = 15 V	IXSH 24N60U1 IXSH 24N60AU1	2.2	V
			2.7	V

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$g_{fs}$	$I_C = I_{C90}$ ; $V_{CE} = 10$ V, Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $\leq 2\%$	9	13	S
$I_{C(on)}$	$V_{GE} = 15$ V, $V_{CE} = 10$ V	65		A
$C_{ies}$ $C_{oes}$ $C_{res}$	$V_{CE} = 25$ V, $V_{GE} = 0$ V, $f = 1$ MHz	1800 200 45		pF
$Q_g$ $Q_{ge}$ $Q_{gc}$	$I_C = I_{C90}$ , $V_{GE} = 15$ V, $V_{CE} = 0.5 V_{CES}$	75 20 35	90 30 50	nC
$t_{d(on)}$ $t_{ri}$ $t_{d(off)}$ $t_{fi}$ $E_{off}$	Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}$ , $V_{GE} = 15$ V, $L = 100 \mu\text{H}$ , $V_{CE} = 0.8 V_{CES}$ , $R_G = R_{off} = 10 \Omega$ Remarks: Switching times may increase for $V_{CE}$ (Clamp) $> 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$	100 200 450 500 275 2		ns ns ns ns ns mJ
$t_{d(on)}$ $t_{ri}$ $E_{on}$ $t_{d(off)}$ $t_{fi}$ $E_{off}$	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}$ , $V_{GE} = 15$ V, $L = 100 \mu\text{H}$ , $V_{CE} = 0.8 V_{CES}$ , $R_G = R_{off} = 10 \Omega$ Remarks: Switching times may increase for $V_{CE}$ (Clamp) $> 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$	100 200 1.8 475 600 450 4 3		ns ns mJ ns ns ns mJ mJ
$R_{thJC}$ $R_{thCK}$		0.25	0.83	K/W K/W

TO-247 AD (IXSH) Outline



Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

## Reverse Diode (FRED)

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_F$	$I_F = I_{C90}$ , $V_{GE} = 0$ V, Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2\%$		1.6	V
$I_{RM}$ $t_{rr}$	$I_F = I_{C90}$ , $V_{GE} = 0$ V, $-di_F/dt = 240 \text{ A}/\mu\text{s}$ $V_R = 360$ V $T_J = 125^\circ\text{C}$ $I_F = 1$ A; $-di/dt = 100 \text{ A}/\mu\text{s}$ ; $V_R = 30$ V $T_J = 25^\circ\text{C}$	10 150 35	15 ns 50	A ns ns
$R_{thJC}$			1	K/W